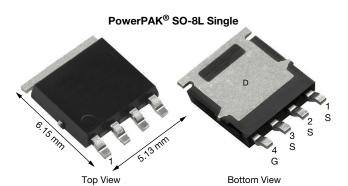


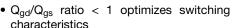
N-Channel 25 V (D-S) MOSFET



PRODUCT SUMMARY						
V _{DS} (V)	25					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.00074					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5 \text{ V}$	0.00140					
Q _g typ. (nC)	39					
I _D (A) ^a	201					
Configuration	Single					

FEATURES

- TrenchFET® Gen IV power MOSFET
- \bullet Tuned for the lowest $R_{DS}\text{-}Q_{oss}$ FOM
- 100 % Rq and UIS tested

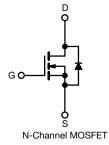






APPLICATIONS

- · Synchronous rectification
- High power density DC/DC
- Hot-swap switch and OR-ing FET
- · Battery and load switch



ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SiJA22DP-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unles	s otherwise note	d)	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	25	V
Gate-source voltage		V _{GS}	+20, -16	7 °
	T _C = 25 °C		201	
Ocalia a adaia a saal (T. 450.00)	T _C = 70 °C		161	
Continuous drain current (T _J = 150 °C)	T _A = 25 °C	I _D	64 ^{b, c}	1
	T _A = 70 °C		51 ^{b, c}	1 ,
Pulsed drain current (t = 100 μs)		I _{DM}	160	1 A
Continuous assurant disable surrent	T _C = 25 °C		43.6	1
Continuous source-drain diode current	T _A = 25 °C	l _S	4.3 b, c	1
Single pulse avalanche current L = 0.1 mH		I _{AS}	50	1
Single pulse avalanche energy	L = 0.1 MH	E _{AS}	125	mJ
	T _C = 25 °C		48	
A. C.	T _C = 70 °C		30.7	100
Maximum power dissipation	T _A = 25 °C	= 25 °C P _D 4.8 b, c W	7 vv	
	T _A = 70 °C		3 b, c	1
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C
Soldering recommendations (peak temperature) d, e			260]

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient b, f	t ≤ 10 s	R _{thJA}	22	26	°C/W
Maximum junction-to-case (drain)	Steady state	R _{thJC}	1.7	2.6	C/VV

Notes

- a. $T_C = 25 \,^{\circ}C$
- b. Surface mounted on 1" x 1" FR4 board
- See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection

 Rework conditions: manual soldering with a soldering iron is not recommended for leadless component Maximum under steady state conditions is 70 °C/W



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static	<u> </u>			l		
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	25	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = 10 mA	-	15.8	-	1400
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-5.1	-	mV/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	1.1	-	2.2	V
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = +20, -16 \text{ V}$	-	-	± 100	nA
		V _{DS} = 25 V, V _{GS} = 0 V	-	-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 25 V, V _{GS} = 0 V, T _J = 55 °C	-	-	10	μΑ
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30	-	-	Α
.		$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	0.00057	V 15.8 - mV/°C -5.1 - 2.2 V - ±100 nA - 1 μA - 10 - A 0.00057 0.00074 0.00140 155 - S 6500 - 2250 - pF 202 - 0.031 - 83 125 39 59 18 - 9 18 - 9.8 - 57 86 1.0 2.0 Ω 15 30 6 12 39 80 6 12 39 80 6 12 39 80 6 12 39 80 6 12 37 80 78 160 41 80 15 30	
Drain-source on-state resistance a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$	-	0.00103	0.00140	Ω
Forward transconductance a	9 _{fs}	V _{DS} = 10 V, I _D = 25 A	-	155	-	S
Dynamic ^b		- -				
Input capacitance	C _{iss}		-	6500	-	
Output capacitance	C _{oss}		-	2250	-	pF
Reverse transfer capacitance	C _{rss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	= 15 V, V _{GS} = 0 V, f = 1 MHz - 202 - 0.031 = 15 V, V _{GS} = 10 V, I _D = 15 A - 83 - 39		-	1
C _{rss} /C _{iss} ratio			-	0.031	-	
	_	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 15 A	-	83	125	
Total gate charge	Q _g		-	39	59	
Gate-source charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$	-	18	-	nC
Gate-drain charge	Q _{qd}	30 . 40 . 2	_	9.8	-	
Output charge	Q _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}$	-	57	86	
Gate resistance	R _q	f = 1 MHz	0.2	1.0	2.0	Ω
Turn-on delay time	t _{d(on)}		-	15	30	
Rise time	tr	$V_{DD} = 10 \text{ V. B}_{L} = 1 \text{ O.}$	-	6	12	
Turn-off delay time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	39	80	
Fall time	t _f		-	6	12	
Turn-on delay time	t _{d(on)}		-	37	80	ns
Rise time	t _r	$V_{DD} = 10 \text{ V. R}_1 = 1 \Omega$	-	78	160	
Turn-off delay time	t _{d(off)}	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		41	80	
Fall time	t _f		-	15	30	
Drain-Source Body Diode Characteristic	s			L		
Continuous source-drain diode current	Is	T _C = 25 °C	-	-	43.6	
Pulse diode forward current (t = 100 μs)	I _{SM}		-	-	160	А
Body diode voltage	V _{SD}	I _S = 10 A	-	0.74	1.1	V
Body diode reverse recovery time	t _{rr}	-	-	50	100	ns
Body diode reverse recovery charge	Q _{rr}	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	60	120	nC
Reverse recovery fall time	ta	$T_J = 25 ^{\circ}\text{C}$	-	27	-	
Reverse recovery rise time	t _b		-	23	-	ns

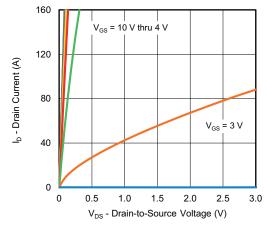
Notes

- a. Pulse test; pulse width $\leq 300~\mu\text{s},$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing

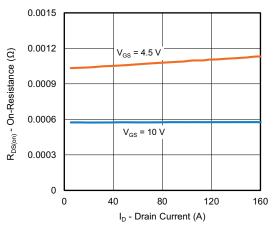
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



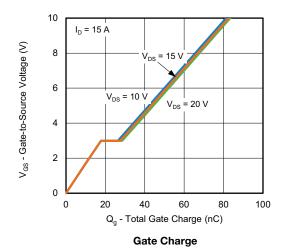
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Output Characteristics

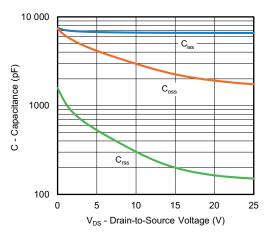


On-Resistance vs. Drain Current

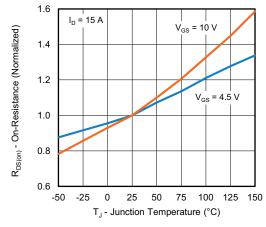


160 (E) 120 80 T_c = 125 °C T_c = -55 °C T_c = -55 °C V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics



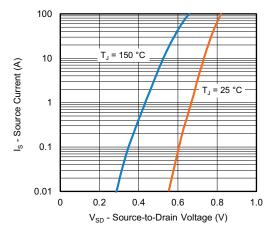
Capacitance



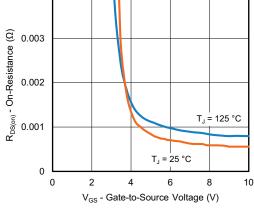
On-Resistance vs. Junction Temperature



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

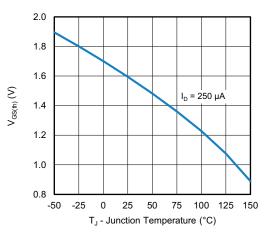


Source-Drain Diode Forward Voltage

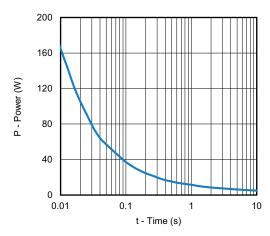


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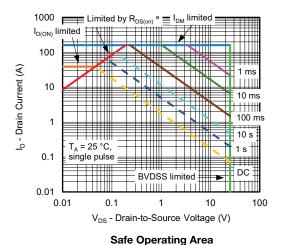
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

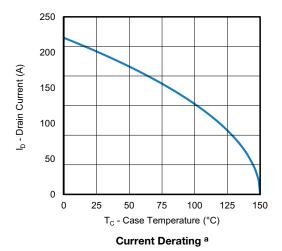


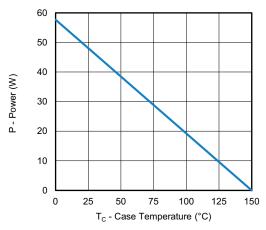
Single Pulse Power, Junction-to-Ambient



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





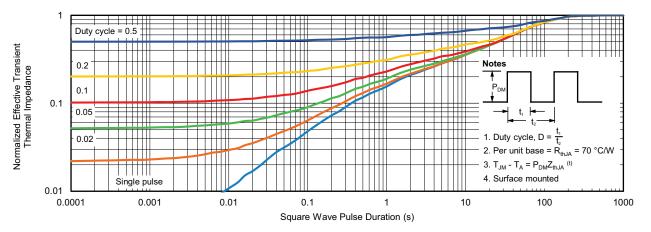
Power, Junction-to-Case

Note

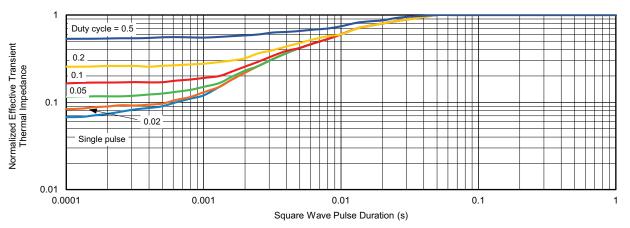
a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

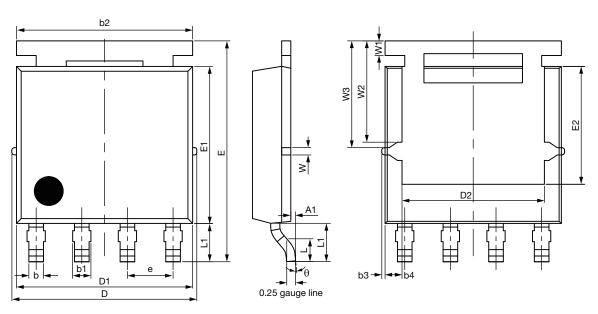


Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?78024.

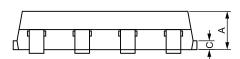


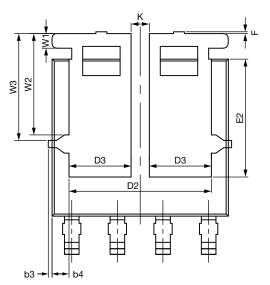
PowerPAK® SO-8L Case Outline 1



Topside view

Backside view (single)





Backside view (dual)



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DIM.		MILLIMETERS			INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
Α	1.00	1.07	1.14	0.039	0.042	0.045		
A1	0.00	-	0.127	0.00	-	0.005		
b	0.33	0.41	0.48	0.013	0.016	0.019		
b1	0.44	0.51	0.58	0.017	0.020	0.023		
b2	4.80	4.90	5.00	0.189	0.193	0.197		
b3		0.094	•		0.004			
b4		0.47			0.019			
С	0.20	0.25	0.30	0.008	0.010	0.012		
D	5.00	5.13	5.25	0.197	0.202	0.207		
D1	4.80	4.90	5.00	0.189	0.193	0.197		
D2	3.86	3.96	4.06	0.152	0.156	0.160		
D3	1.63	1.73	1.83	0.064	0.068	0.072		
е		1.27 BSC	•	0.050 BSC				
E	6.05	6.15	6.25	0.238	0.242	0.246		
E1	4.27	4.37	4.47	0.168	0.172	0.176		
E2	3.18	3.28	3.38	0.125	0.129	0.133		
F	-	-	0.15	-	-	0.006		
L	0.62	0.72	0.82	0.024	0.028	0.032		
L1	0.92	1.07	1.22	0.036	0.042	0.048		
K		0.51		0.020				
W	0.23		0.009					
W1	0.41		0.016					
W2	2.82			0.111				
W3		2.96			0.117			
θ	0°	-	10°	0°	-	10°		

ECN: S19-0643-Rev. E, 05-Aug-2019

DWG: 5976

Note

• Millimeters will gover



RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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